XP04114 (XP4114)

Silicon PNP epitaxial planar type

For switching/digital circuits

Features

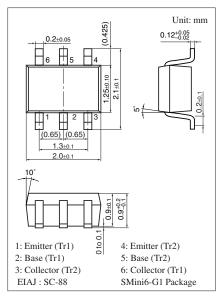
- Two elements incorporated into one package (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

Basic Part Number

• UNR2114 (UN2114) × 2

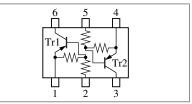
Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	-50	V
Collector-emitter voltage (Base open)	V _{CEO}	-50	V
Collector current	I _C	-100	mA
Total power dissipation	P _T	150	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



Marking Symbol: BK

Internal Connection



Symbol Conditions Parameter Min Тур Max Unit Collector-base voltage (Emitter open) V_{CBO} $I_{C} = -10 \ \mu A, I_{E} = 0$ -50v $I_{C} = -2 \text{ mA}, I_{B} = 0$ v Collector-emitter voltage (Base open) -50V_{CEO} $V_{CB} = -50 \text{ V}, I_E = 0$ Collector-base cutoff current (Emitter open) -0.1μΑ I_{CBO} Collector-emitter cutoff current (Base open) $V_{CE} = -50 \text{ V}, I_B = 0$ -0.5μΑ I_{CEO} $V_{EB} = -6 V, I_C = 0$ Emitter-base cutoff current (Collector open) -0.2I_{EBO} mA $V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$ Forward current transfer ratio 80 h_{FE} ____ $I_{C} = -10 \text{ mA}, I_{B} = -0.3 \text{ mA}$ Collector-emitter saturation voltage V_{CE(sat)} -0.25V $V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$ Output voltage high-level VOH -4.9 V V Output voltage low-level VOL $V_{CC} = -5 \text{ V}, V_B = -2.5 \text{ V}, R_L = 1 \text{ k}\Omega$ -0.2-30% Input resistance R_1 10 +30% kΩ 0.17 0.21 0.25 Resistance ratio R_1 / R_2 Transition frequency $V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$ 80 MHz f_T

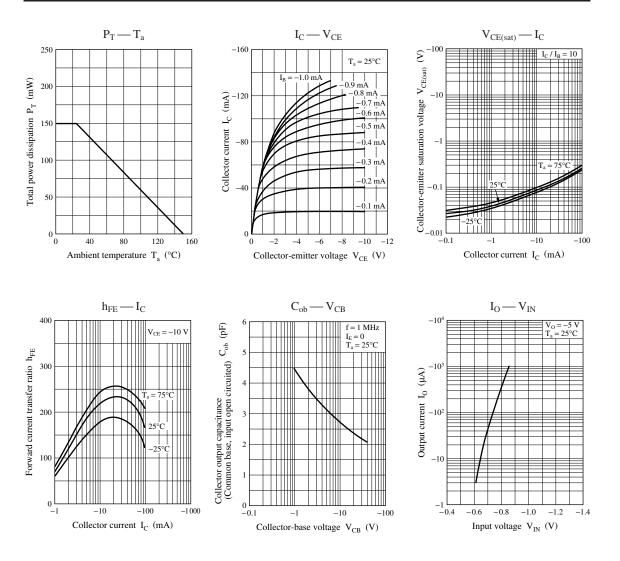
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

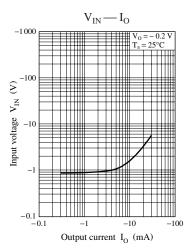
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

Note) The part number in the parenthesis shows conventional part number.

XP04114







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